

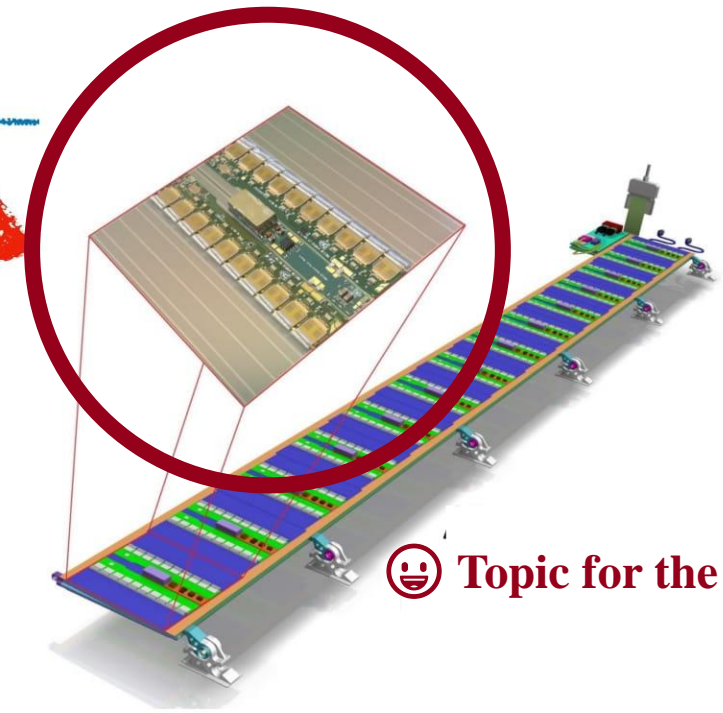
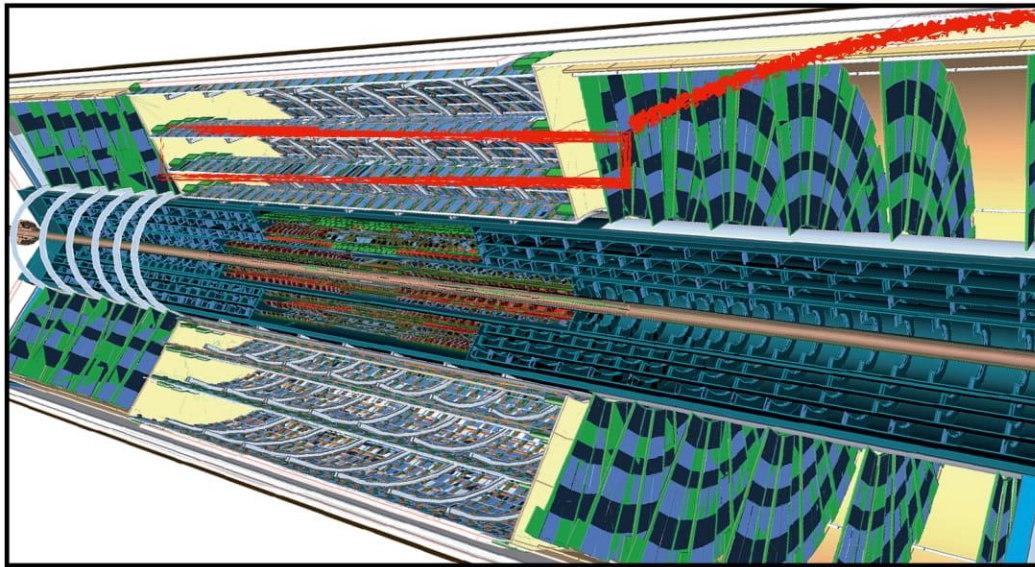
AMAC ASIC for the ATLAS ITk silicon strip detector Design and Verification

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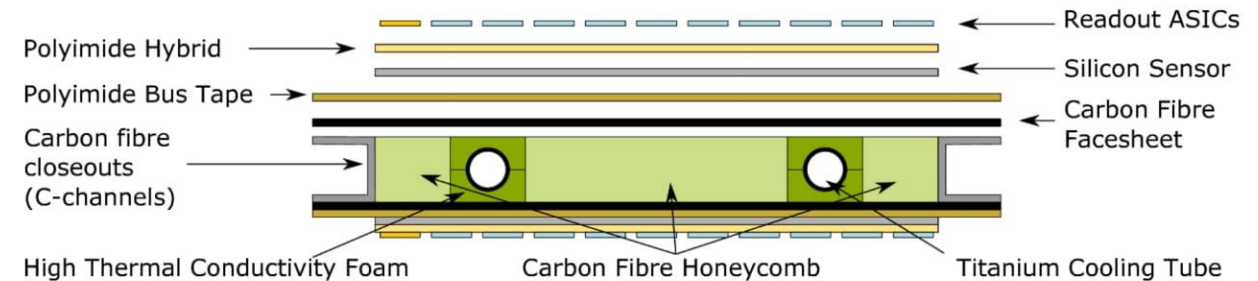


Silicon Strips Stave



😊 Topic for the next hour!

- Staves are the basic units of the ITk Strip Barrel detector
- It is made of a 1.4 m long support structure
 - provides **mechanical rigidity and support** by using high stiffness and high thermal conductivity carbon fiber
 - Provides **cooling** to modules
 - Polyimide bus-tape is co cured on both faces to channel power and data from and to the modules .
- 14 silicon modules are directly glued on both sides of the stave support structure



ATLAS Binary Chip - Star:

“Charged particles passing through the silicon strip sensor will create a signal. Each ABCStar is responsible for 256 strip channel, and signals from each strip are amplified, shaped, and discriminated to provide binary output.”

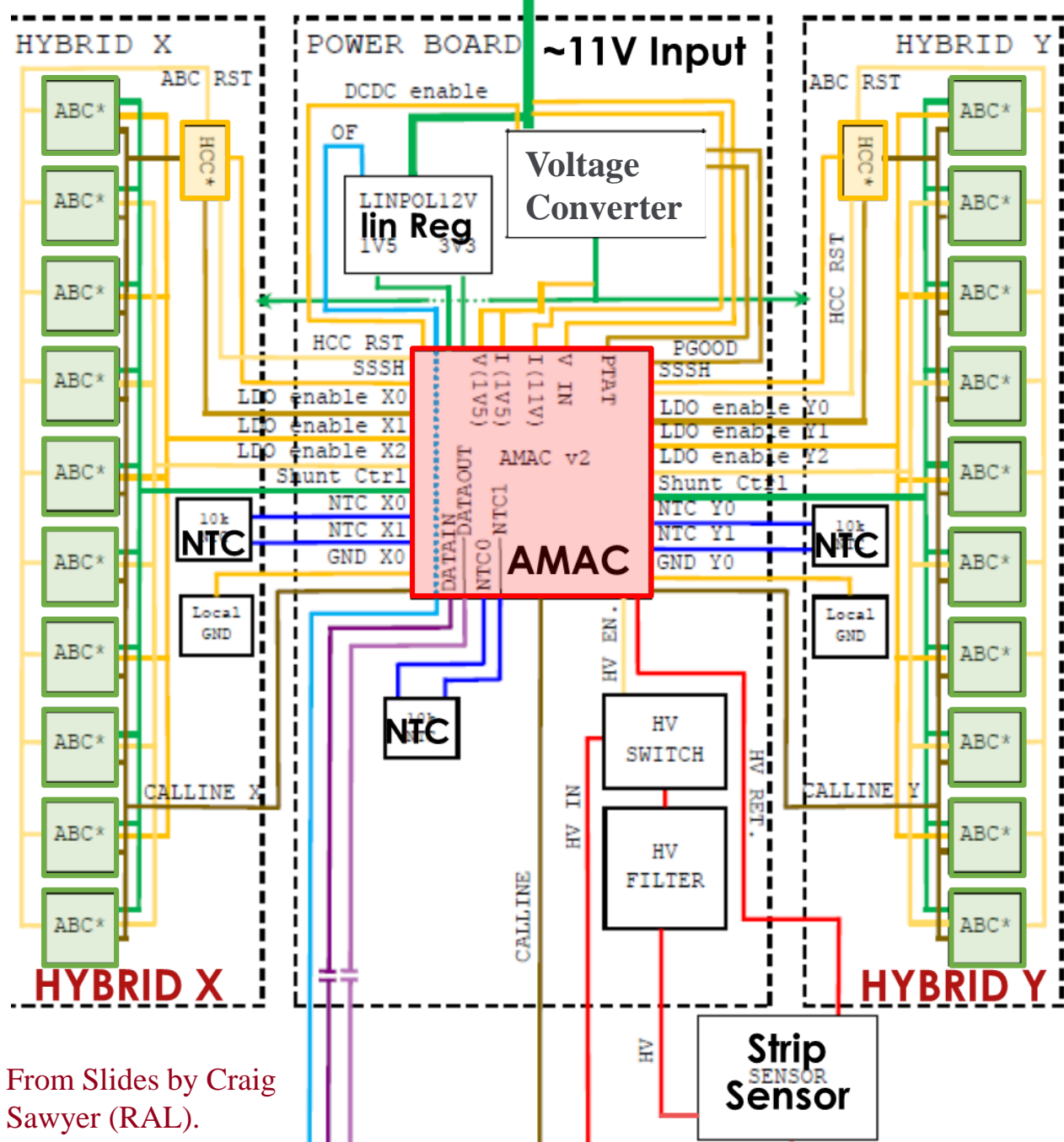
-- ATLAS ITk TDR

Hybrid Controller Chip - Star:

“Each HCCStar receives the signals from up to 12 ABCStar, builds packets and moves them on. It also receives the clock and control signals and distributes those to the ABCStar.”

20× ABCStar

2× HCCStar



From Slides by Craig Sawyer (RAL).

Autonomous Monitor And Control

Why we need the AMAC & How does it help

- Hazards in detector modules
 - Abnormal Temperature:
 - E.g., local high temperature
 - ⇒ bent/damage sensor
 - ⇒ loss of positioning accuracy
 - Abnormal Current:
 - E.g., individual components short
 - ⇒ takes too much power
 - ⇒ high temperature/insufficient supply
 - Abnormal Voltages:
 - All ASICs and Sensor needs proper voltage to work!
 - Low Voltage ~ 1.5V
 - High Voltage ~ 500V

- How does AMAC help?



- **Monitor!**

- “Spotting” the issues in the first place,
- With continuous analog monitoring every 0.5 millisecond.



- **Control!**

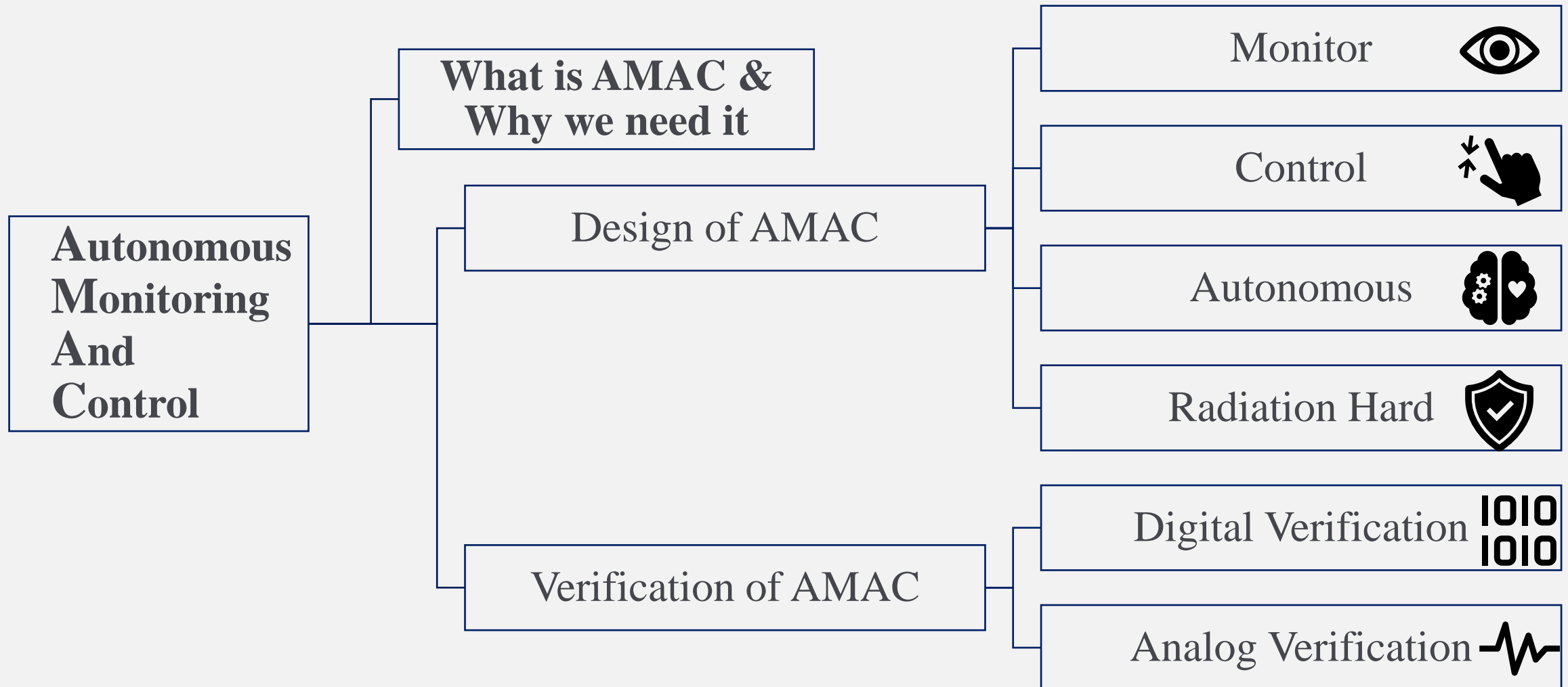
- “Handle” the defective components without dismantling the detector,
- With 5 switches to different components.



- **Autonomous!**

- Quickly isolate the issue & Stop it from spreading,
- By autonomous interlock logic channels.

OUTLINE



Analog Monitoring

Temperature

- Hybrid X/Y Temperature & Power Board Temperature
- Power Supply Temperature
- AMAC Internal Temperature

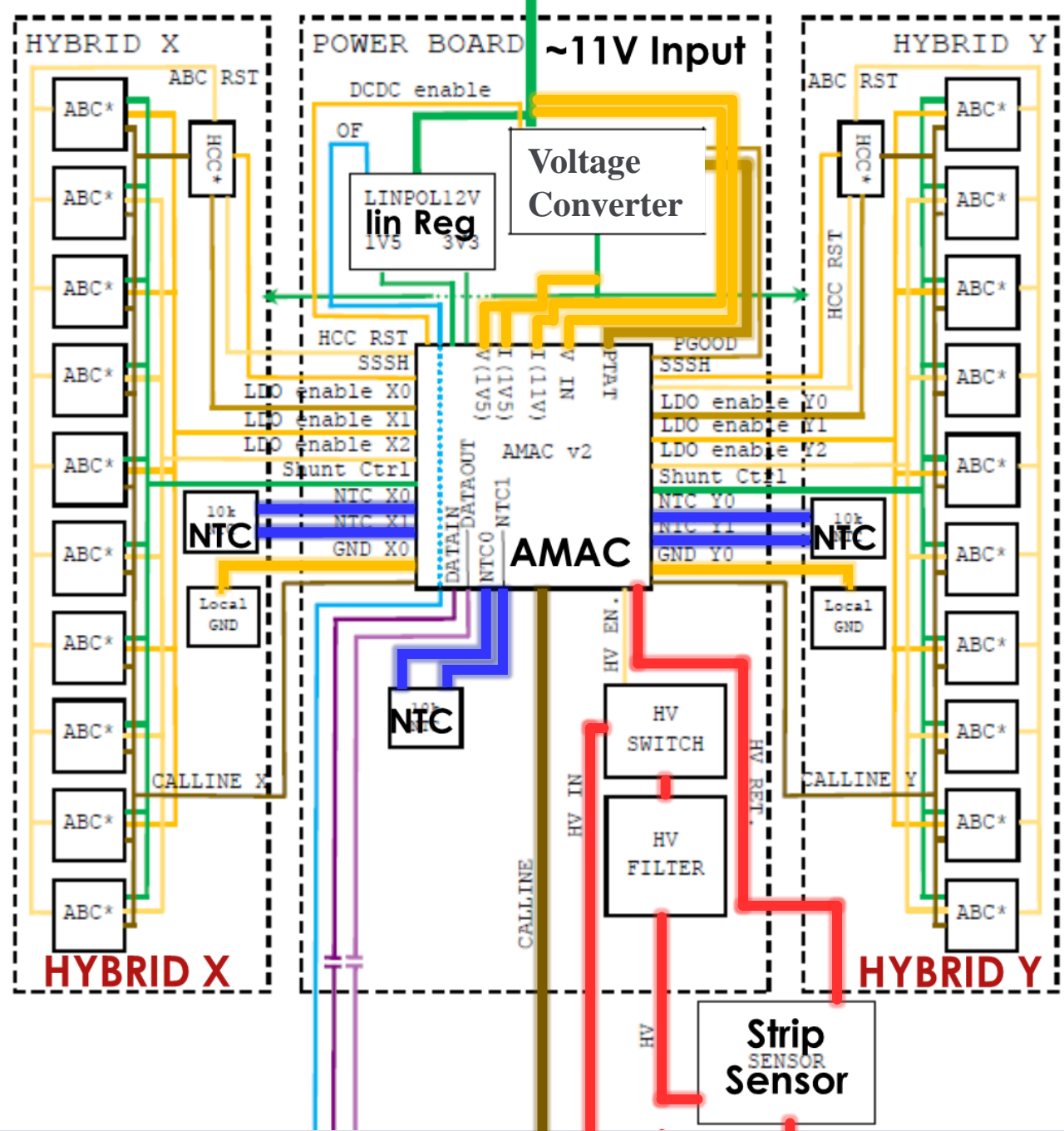
Current

- Silicon Sensor Bias Current (High Voltage Return)
- Voltage Converter Input
- Voltage Converter Output

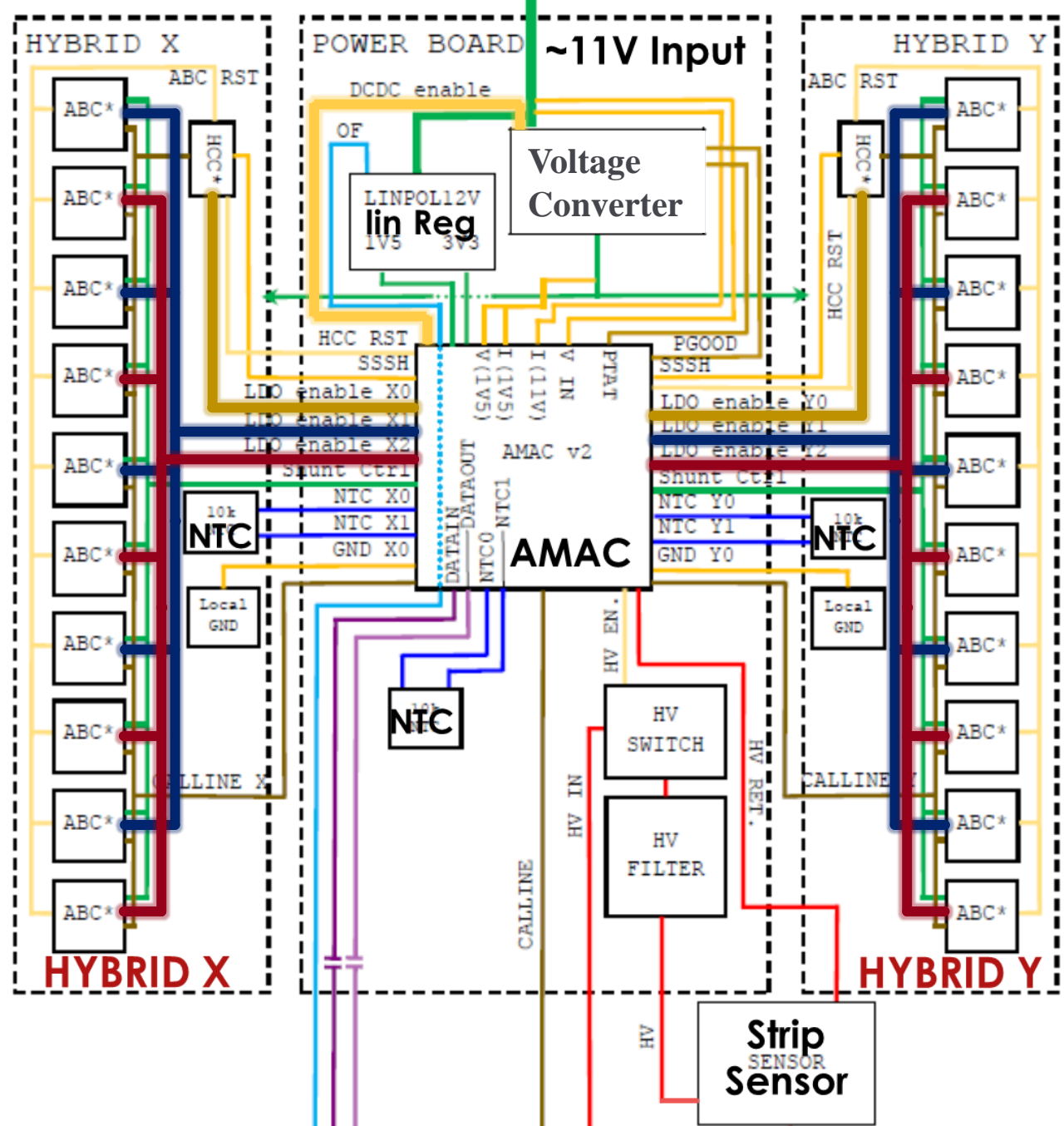
Voltage

- Ground Voltage Calibration (Hybrid X/Y & End-of-Stave)
- Voltage Converter Input
- Voltage Converter Output

Analog to Digital Converter
(16 Multiplexer Channel)



Powering Control



Interlock Switch Output



Hybrid X Low Power	X0: HCCStar X1: 5×ABCStar X2: 5×ABCStar
Hybrid Y Low Power	Y0: HCCStar Y1: 5×ABCStar Y2: 5×ABCStar
Power Enable	Voltage Converter On/Off
High Voltage Switch 0 & 1	HV 0 On/Off HV 1 On/Off
High Voltage Switch 0 & 1	HV 2 On/Off HV 3 On/Off

AMAC Internal

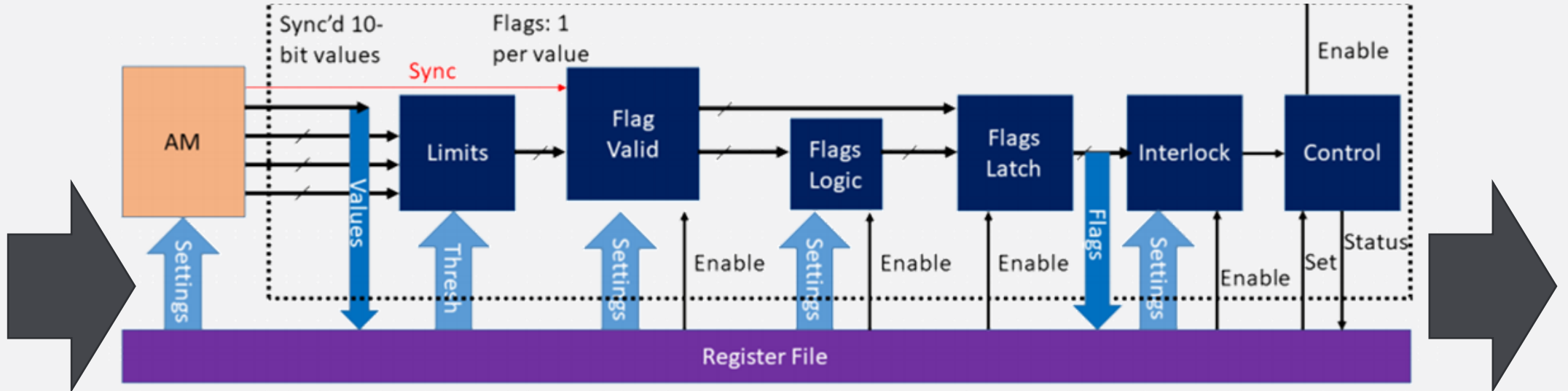


Autonomous Monitor And Control (AMAC)

Analog to Digital Converter
(16 Multiplexer Channel)

Interlock Switch Output

Interlock Channel



Example workflow:

Channel:	Value.	Check?	Flag!
Hybrid X:	10°C	$\leq -10^\circ\text{C}?$	High Flag!
Hybrid Y:	-20°C	$\leq -10^\circ\text{C}?$	No Flag.
Power-board:	-20°C	$\leq -10^\circ\text{C}?$	No Flag.
Total Current:	200mA	$\leq 150\text{mA}?$	High Flag!
...

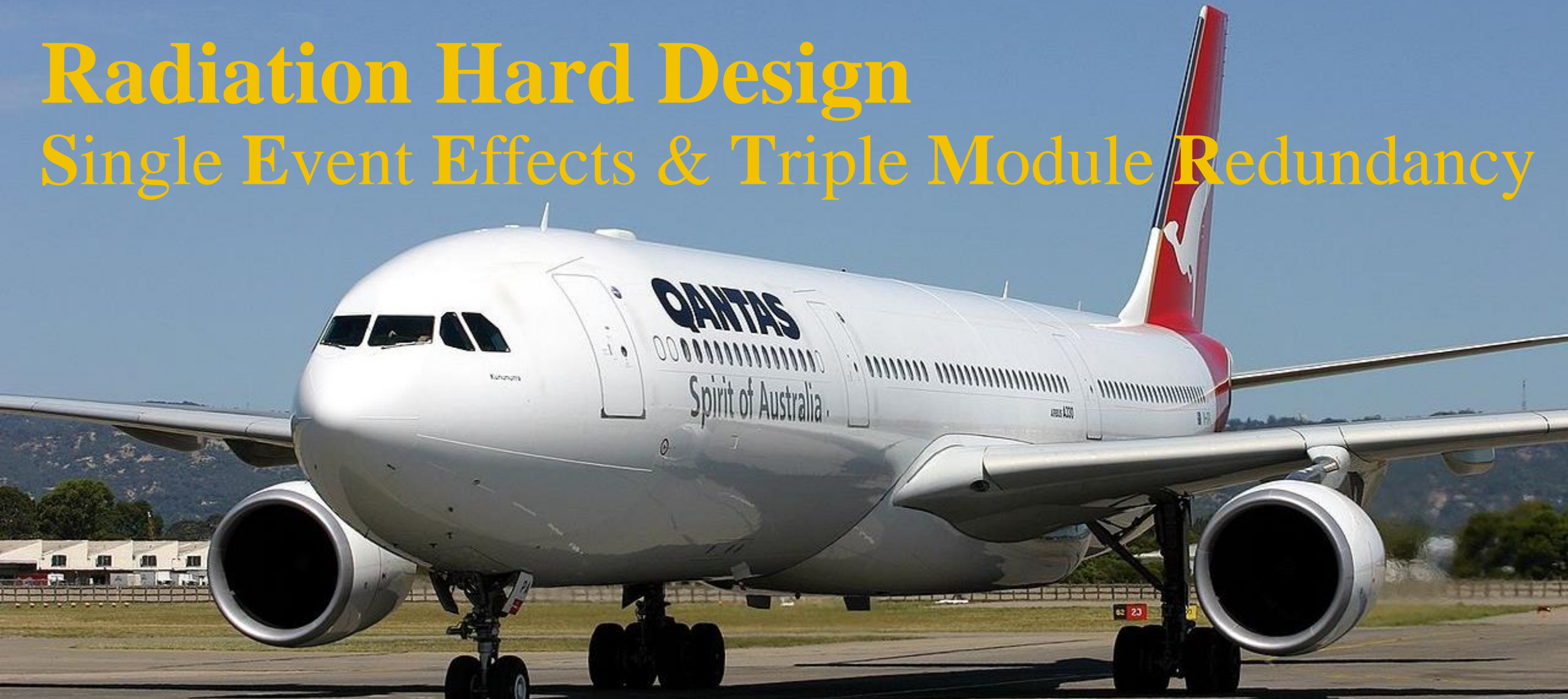
Latch flag to **register** for debugging and analysis...

Move the **interlock state** from **ON** to **LOCK**

Turn All **Hybrid X ASICs** to **Low-Power Mode!**

Radiation Hard Design

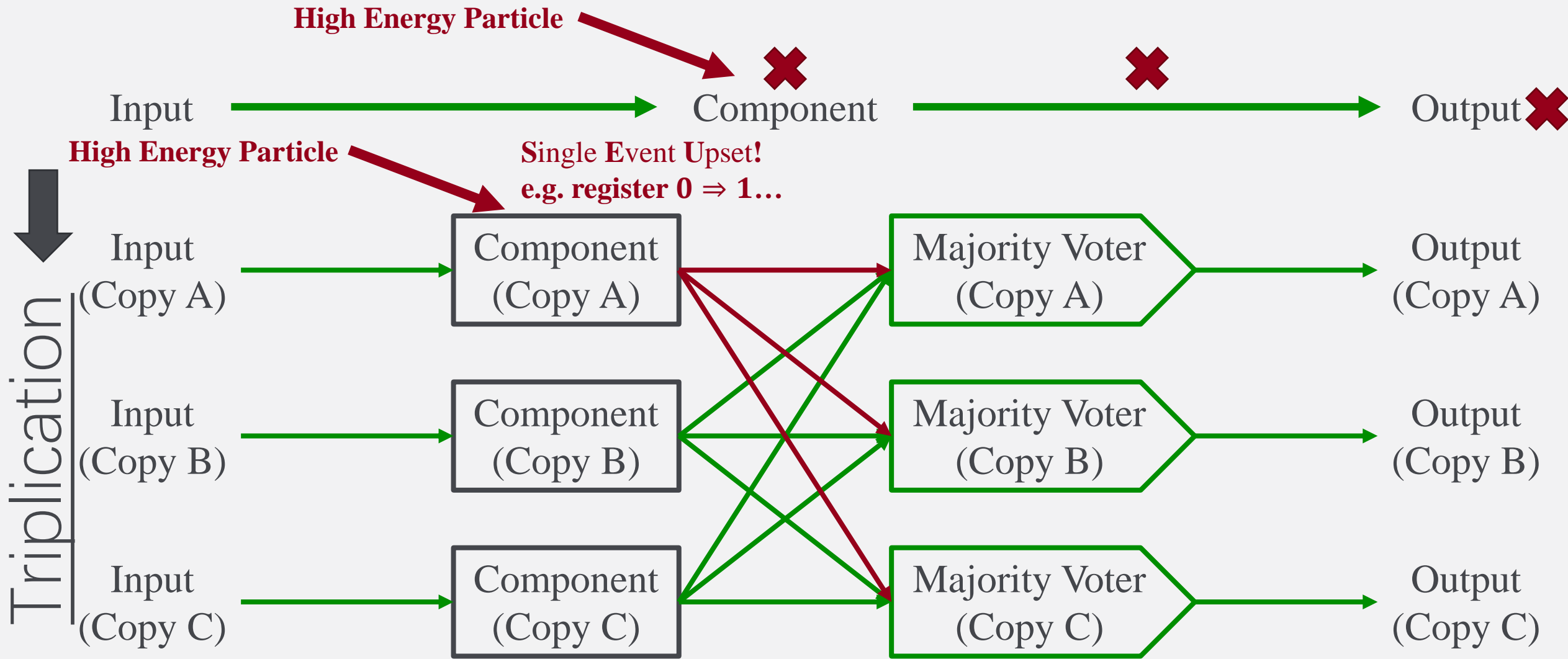
Single Event Effects & Triple Module Redundancy



*“A single event upset in the flight computers of this Airbus A330 during Qantas Flight 72 on 7 October 2008 is suspected to have resulted in an aircraft upset that nearly ended in a crash after the computers experienced several malfunctions.” **Rare event in aviation and daily life, but extremely common in particle collider!***



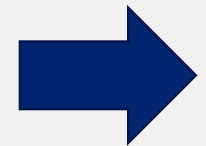
Triple Module Redundancy against SEU & SET



Design Verification: Digital vs Analog

- Digital Logic Block:
 - i) Many revision and updated design version;
 - ii) Relatively independent of the manufacturing;
 - iii) Functions mostly internal;
 - iv) Many scenarios/combinations to be considered!

1010
1010

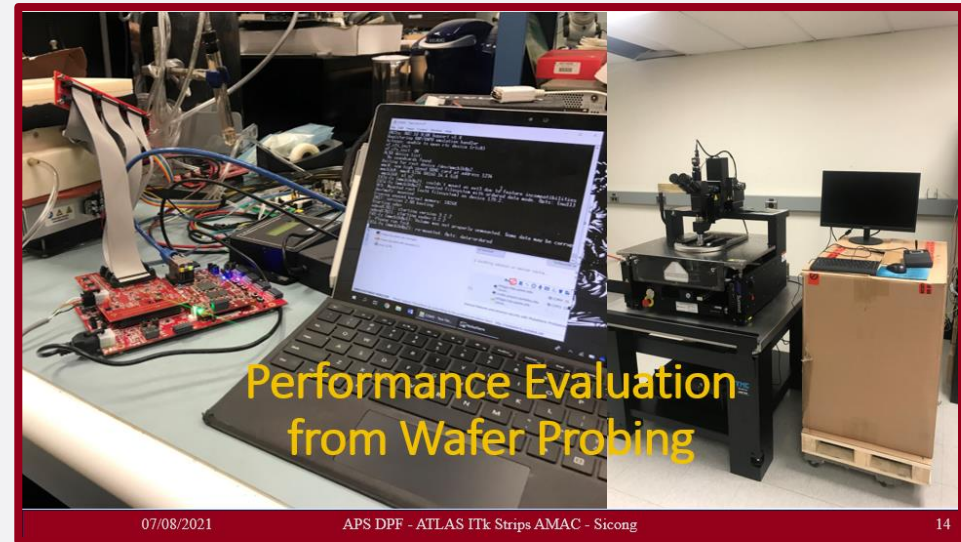
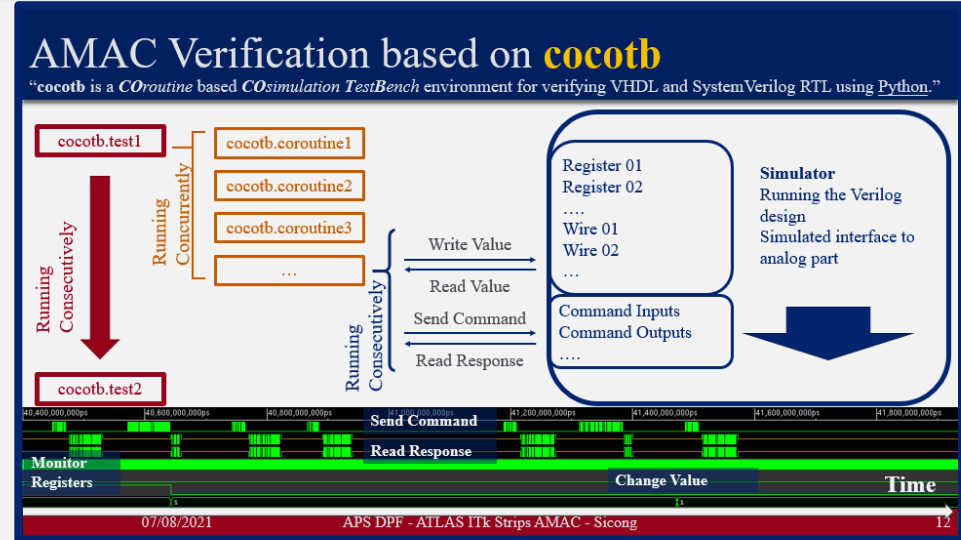


Simulate

- Analog Block:
 - i) Design relatively fixed;
 - ii) Parameters heavily dependent on manufacturing;
 - iii) Needs a real set-up with external devices;
 - iv) Data needed for each chip!

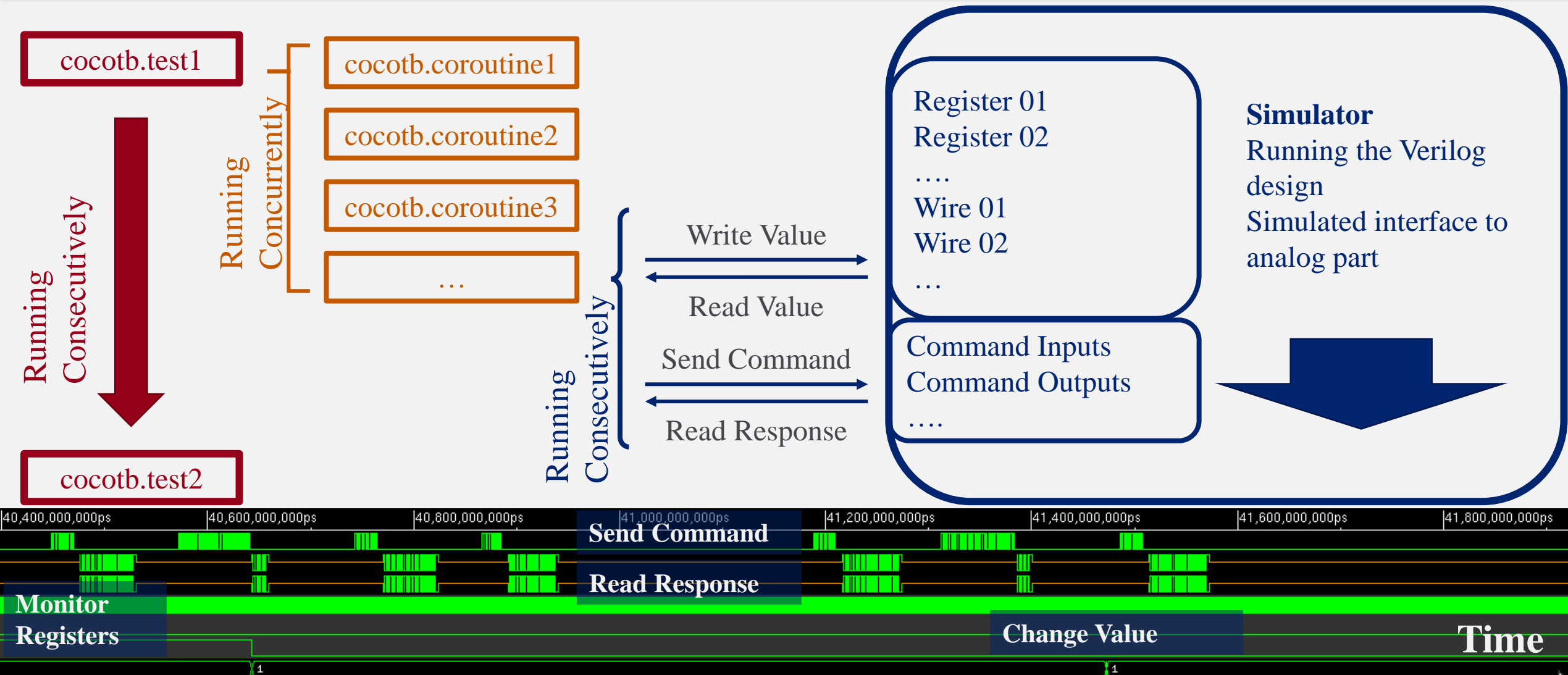


Probe & Fit

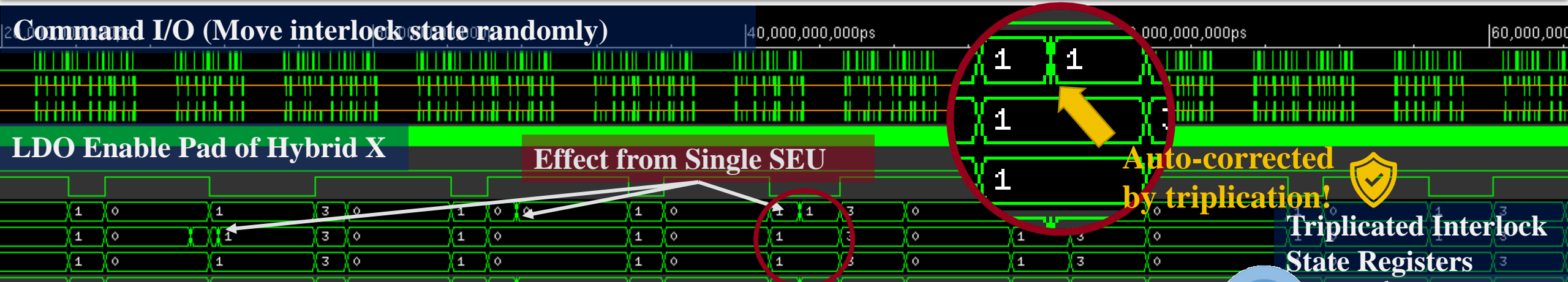


AMAC Verification based on **cocotb**

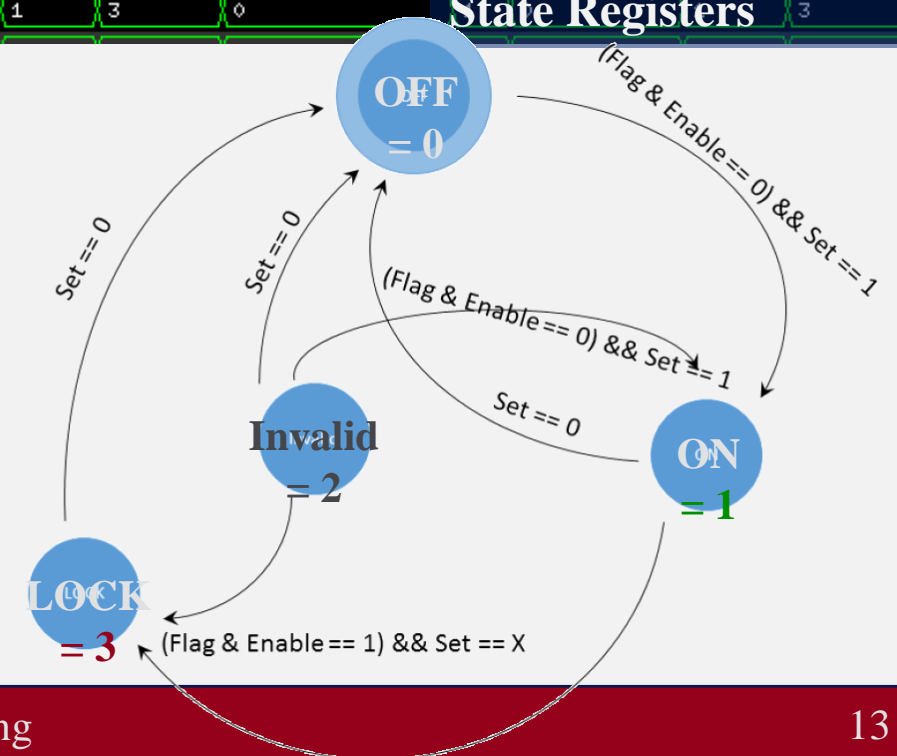
“cocotb is a *CO*routine based *CO*simulation *TestBench* environment for verifying VHDL and SystemVerilog RTL using Python.”

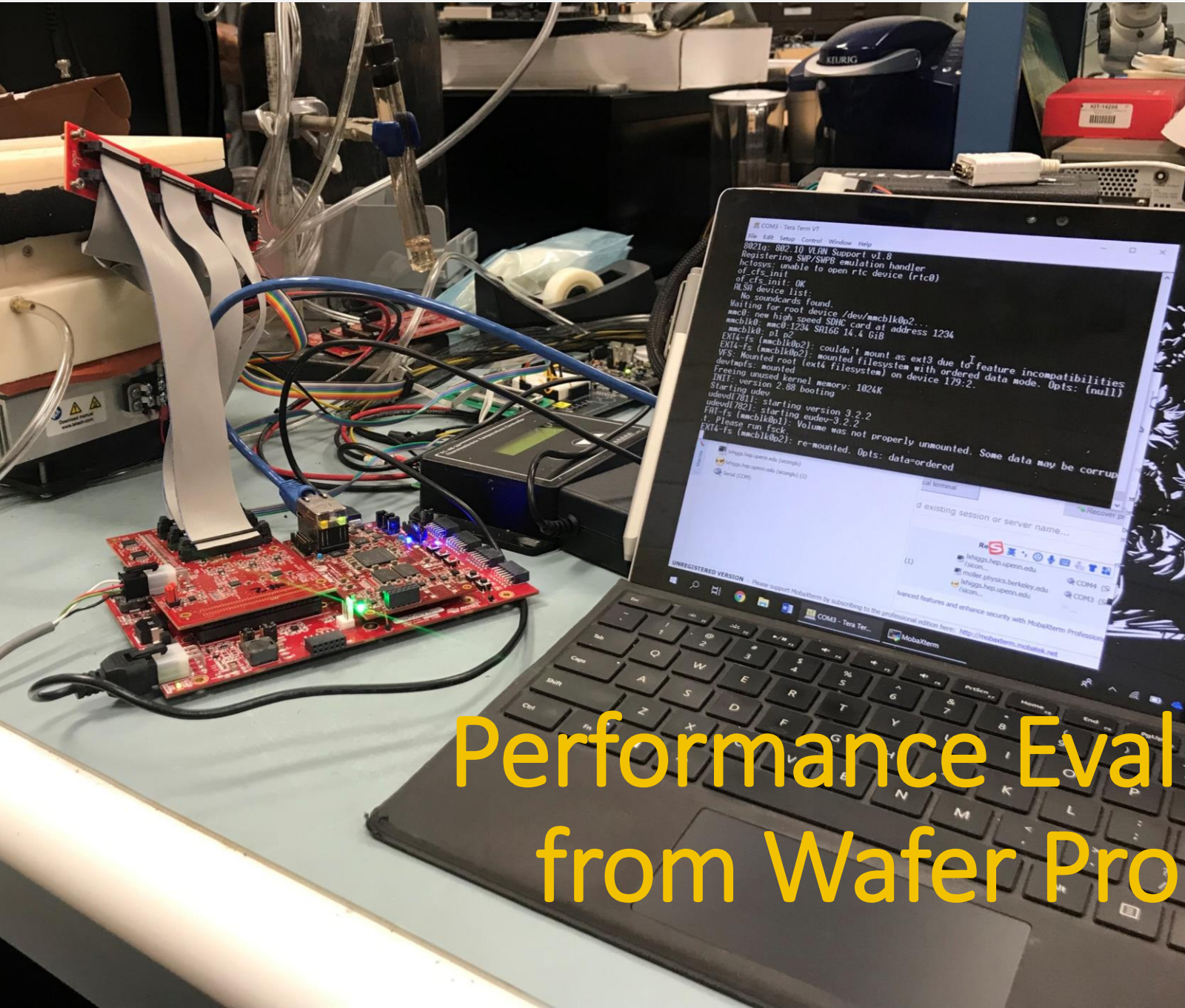


Example Test Routine (Interlock Toggling under single SEU blast)



- **Coroutine #1:**
 - Simulate the interlock move conditions by commands
 - Verify that the resulting interlock states are correct
- **Coroutine #2:**
 - Continuously inflict random Single Event Upset on any register in related interlock channel
- Note that the **triplicated** register correct themselves!





Performance Evaluation from Wafer Probing

Numerical AMAC Performance Evaluation

Voltage
Measurement

Current
Measurement

Temperature
Measurement

Digital-to-
Analog
Output

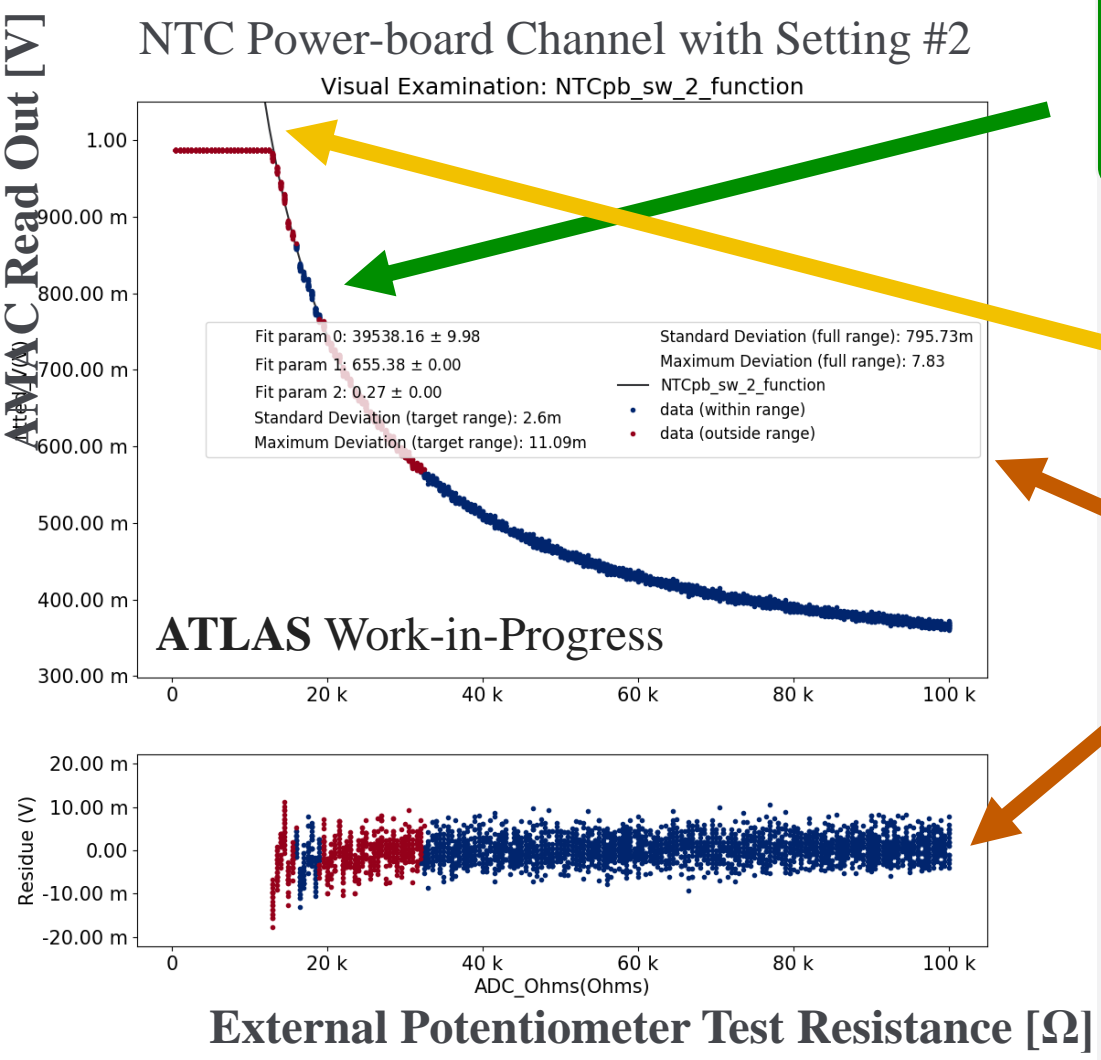
- ✓ Use external digital device to scan the measurement
- ✓ Use AMAC to read the value multiple times
- ✓ Compare input and readout to check that it follows the design
- ✓ Fit to evaluate accuracy & precision

Only NTC measurement will be discussed here as an example of analysis procedure.

Analysis of Individual Tests

e.g. Fit to a simplified circuit model:

$$V_{\text{measure}} = 250\text{mV} \frac{R_{\text{sw}}}{R_{\text{NTC}} + R_{\text{internal}}} + V_{\text{zero}}$$



Collect Data Array

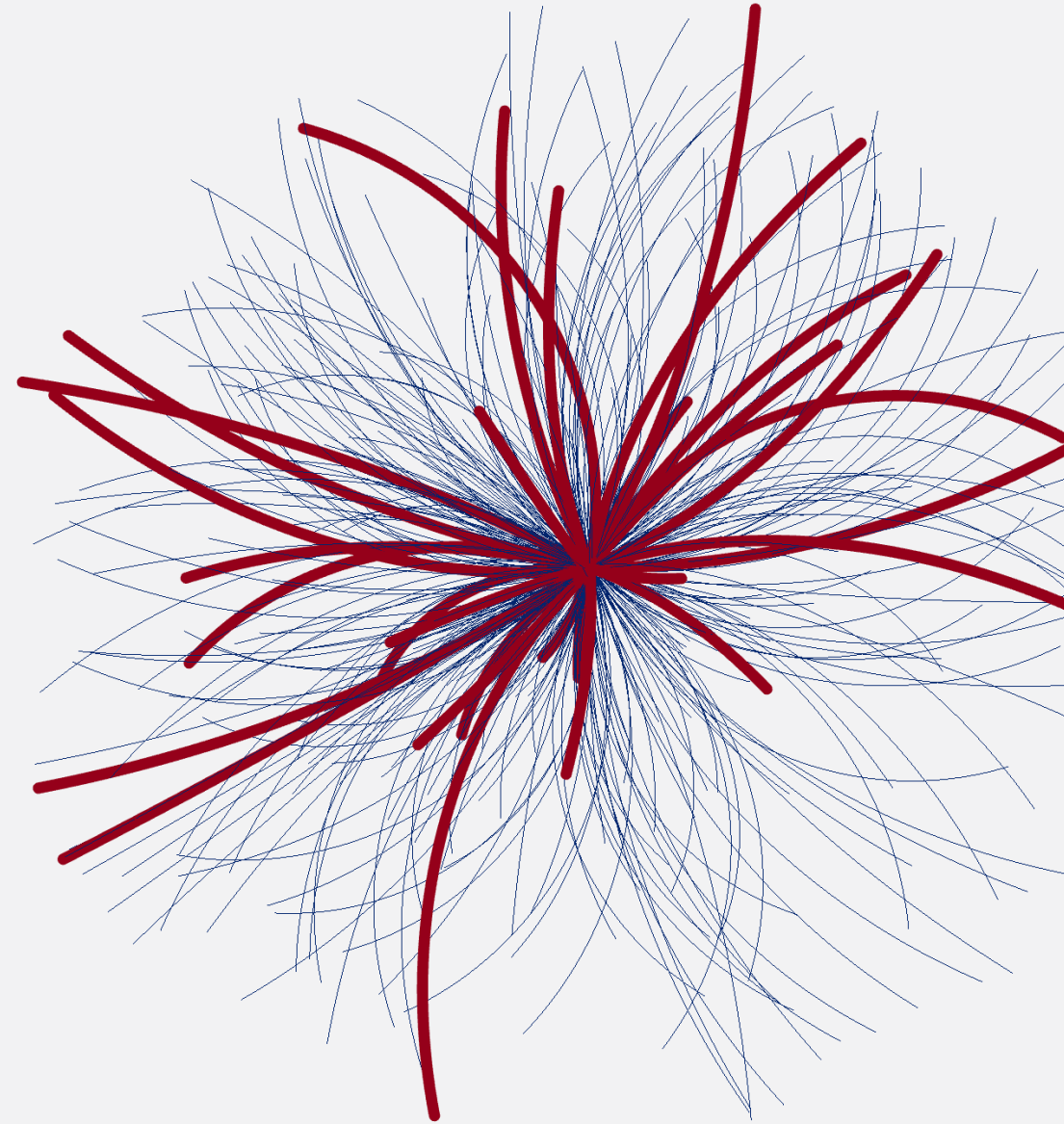
Fit to Designed Function

Numerical Fit Parameter & Residual Parameters

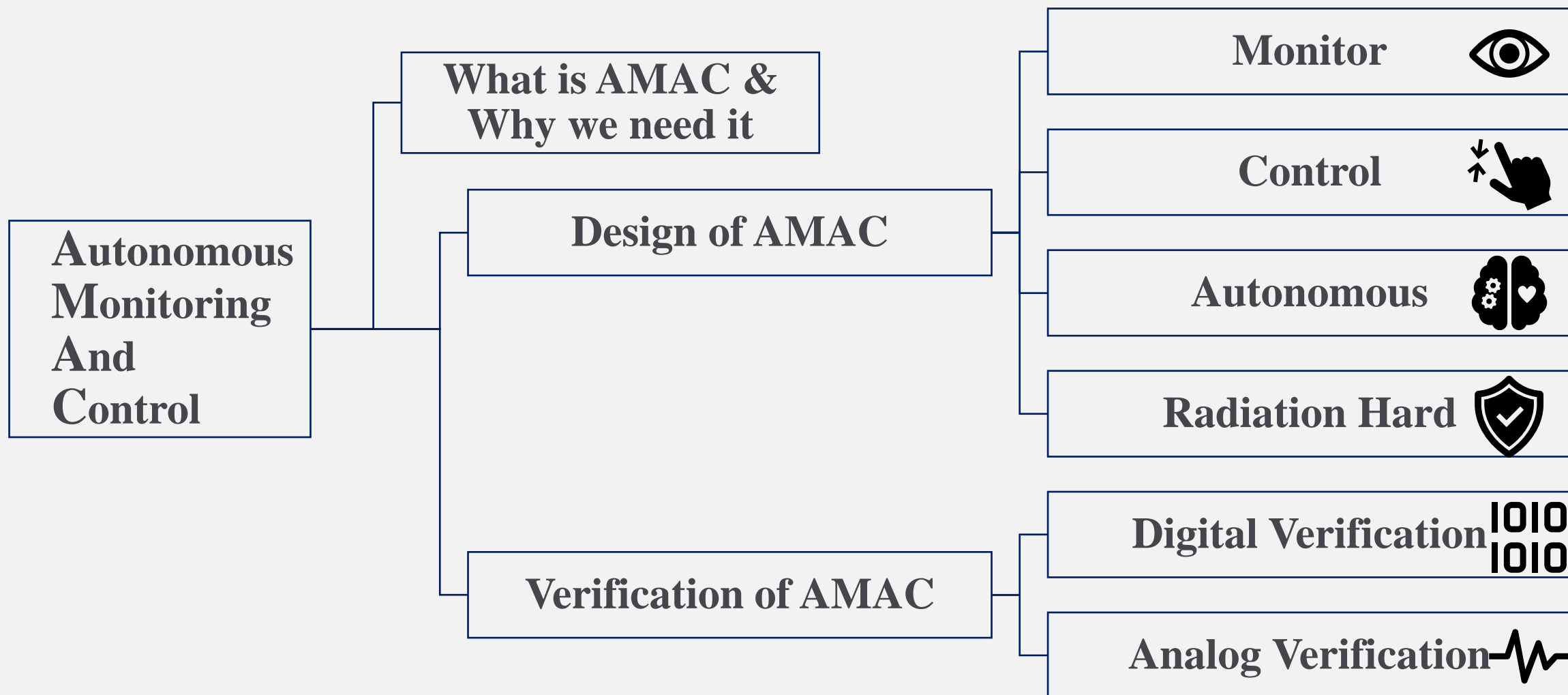
Save Result to Local and Online Database \Rightarrow

The prototype has been exceptionally successful!
Luis will tell you more about it in the next presentation!

*Thank you
for your
attention!!!*



OUTLINE

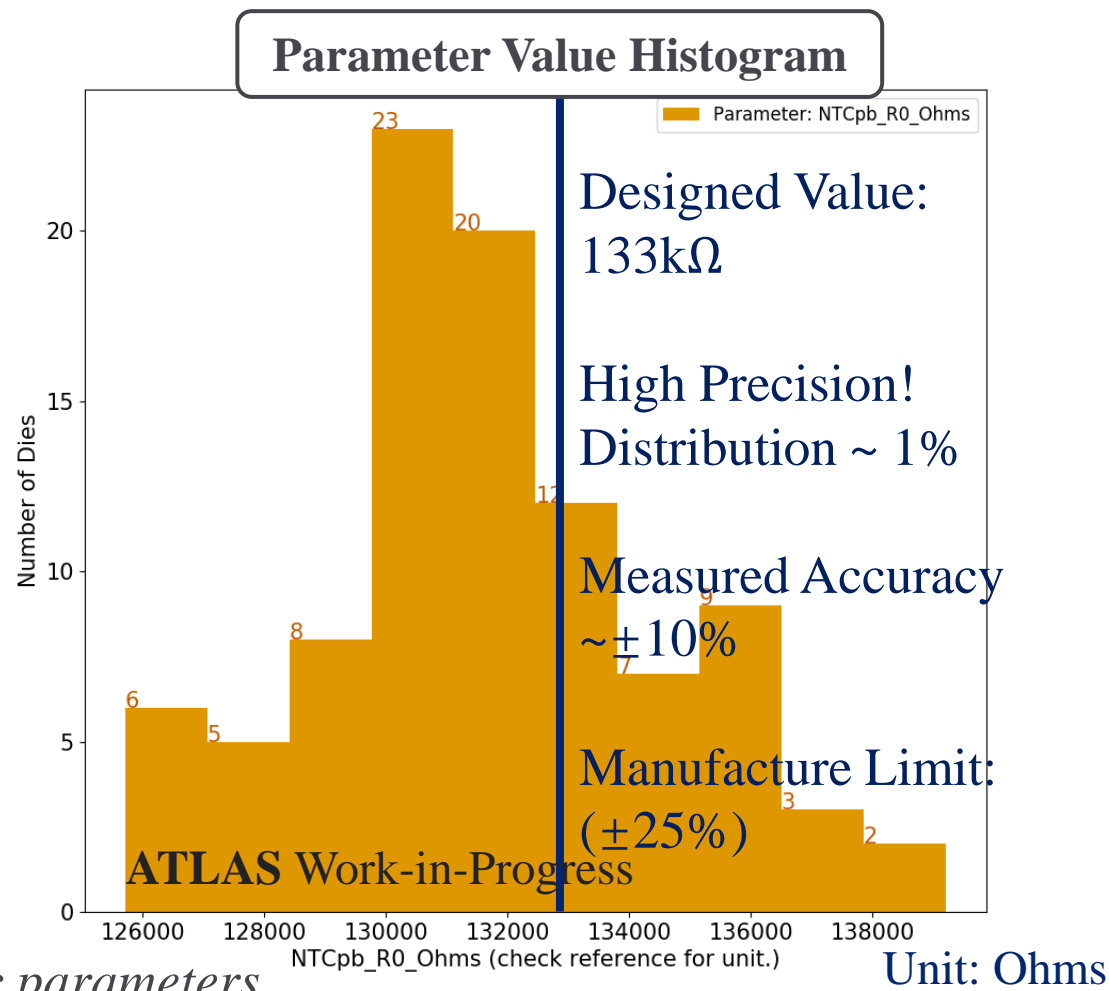
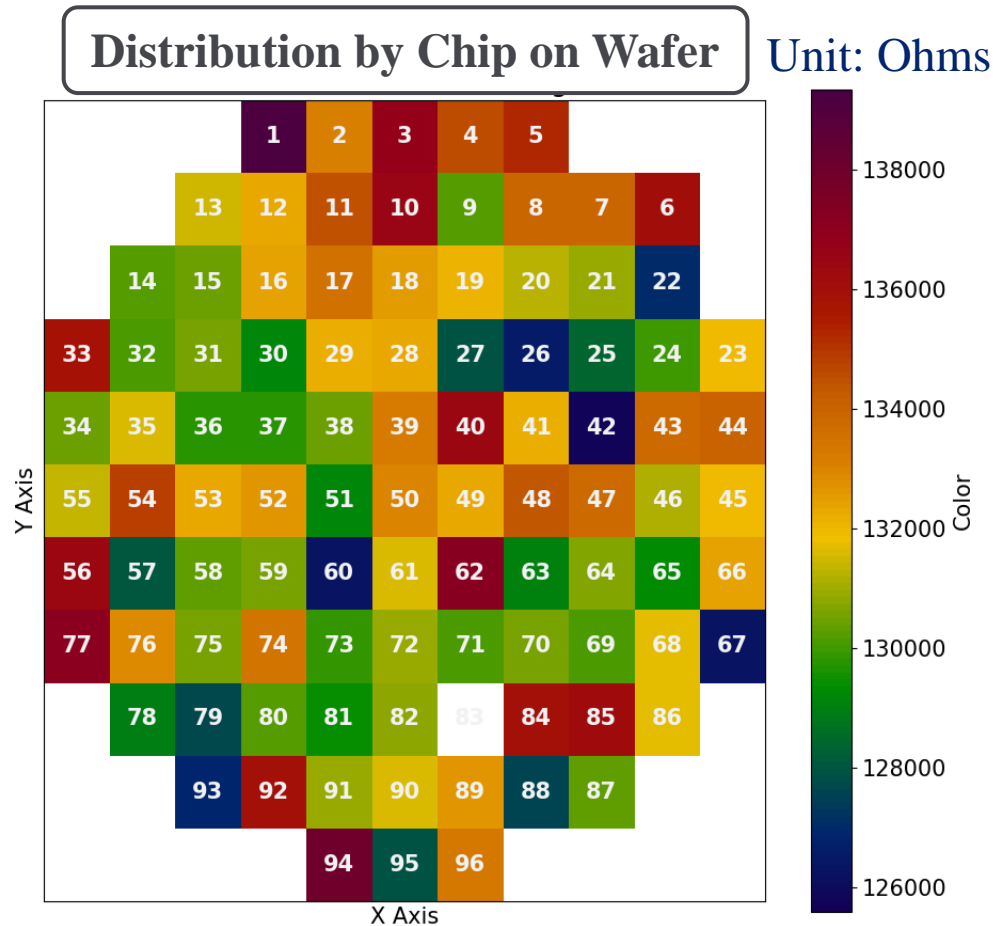


Back-Up

Numerically Fitted Chip Parameter

NTC Power-board Resistance - R_0

Wafer : V0CVRFH
Dice: 95/96 passed



Like this one above, we have:
>1000 collected parameters

>200 analog diagnostic parameters
>50 analog pass/fail parameters

ITk Production Database

<https://itkpd-test.unicorncollege.cz/>

Component Details

Show details of selected Component of the Inner Tracker.

20USG000501034


AMAC Chip - AMACv2a

Basic Properties

ATLAS SERIAL NUMBER

20USG000501034

COMPONENT TYPE

 AMAC Chip AMAC

TYPE

AMACv2a

CURRENT STAGE

Probed at University of Pennsylvania

CURRENT LOCATION

 University of Pennsylvania UPENN

PROJECT

Strips

SUBPROJECT

Strip general

REGISTRATION

03.06.2020 11:44

 Sicong Lu

OWNER INSTITUTE

 University of Pennsylvania UPENN

SHIPMENT DESTINATION

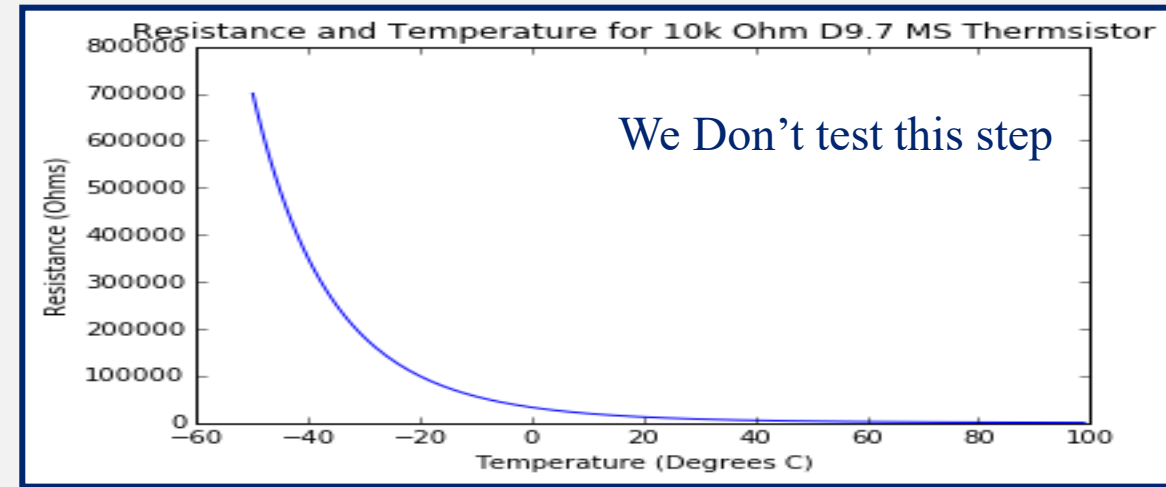
No current shipment destination



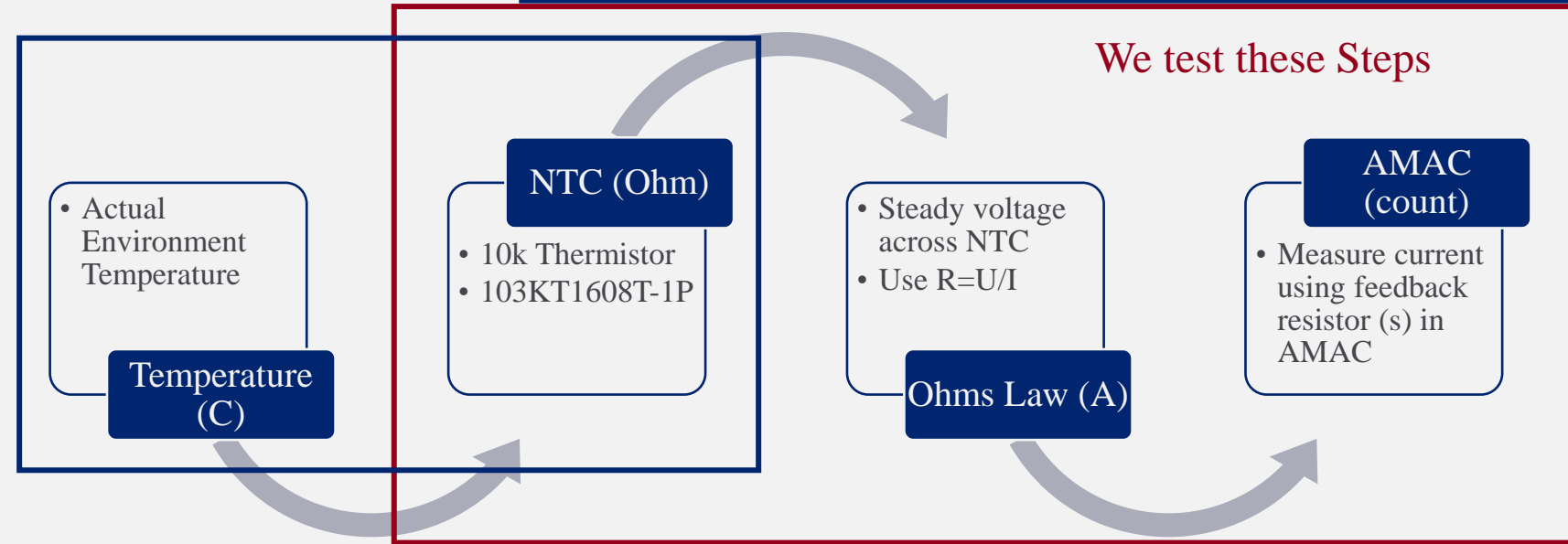
a73982646f2503de102f1bbe27294ca9

Example Temperature Measurement

- The way we measure the temperature:
 - Use industrial NTC
 - Measure Resistance through current
 - Measure Current (through resistor to voltage) by AMAC
- Simple Circuit:
 - Simple amplifier
 - Can measure resistance



We also measure:
BPol12V by PTAT
(proportional to absolute temperature)
AMAC by CTAT
(complementary to absolute temperature)

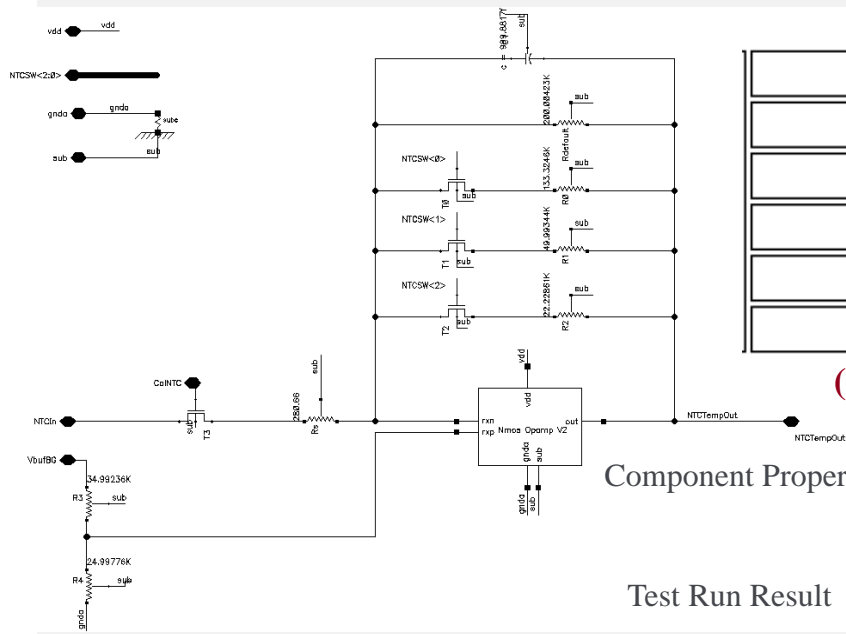
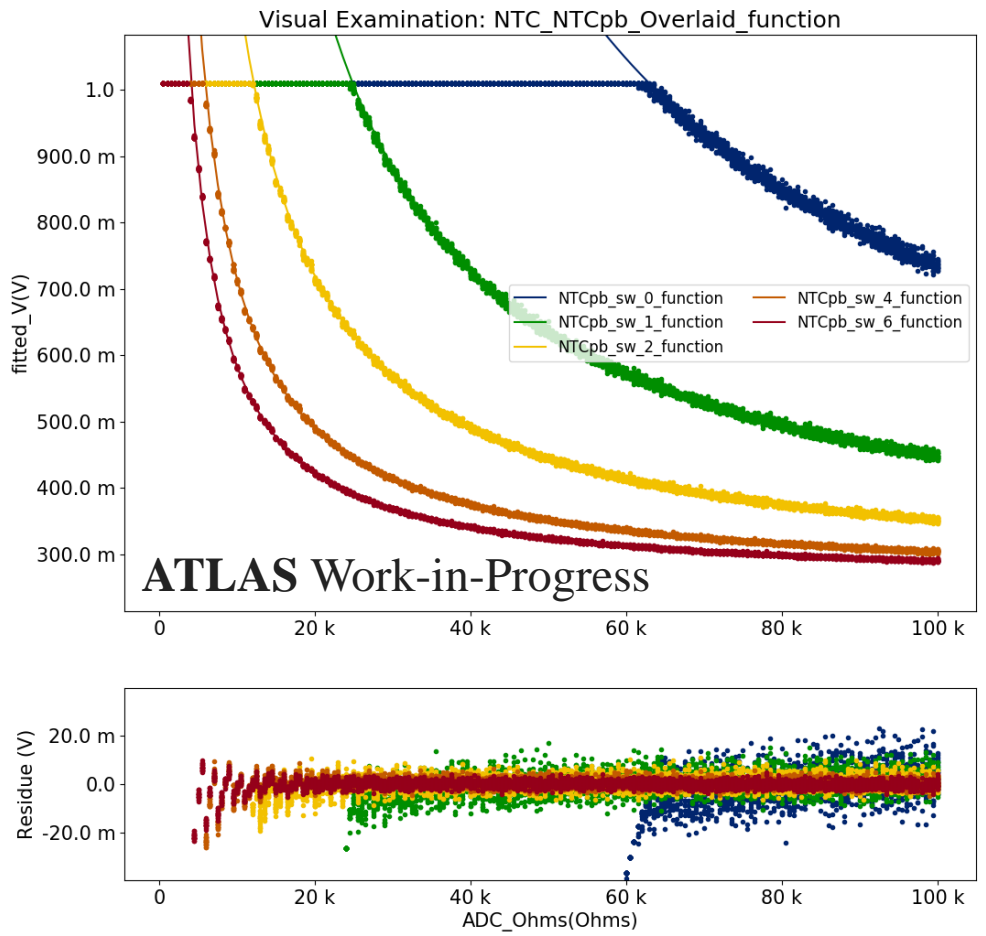


Example: Validation & Fit

Plot Fit by Simplified Circuit Model:

$$V_{\text{measure}} = 250\text{mV} \frac{R_{\text{sw}}}{R_{\text{NTC}} + R_{\text{internal}}} + V_{\text{zero}}$$

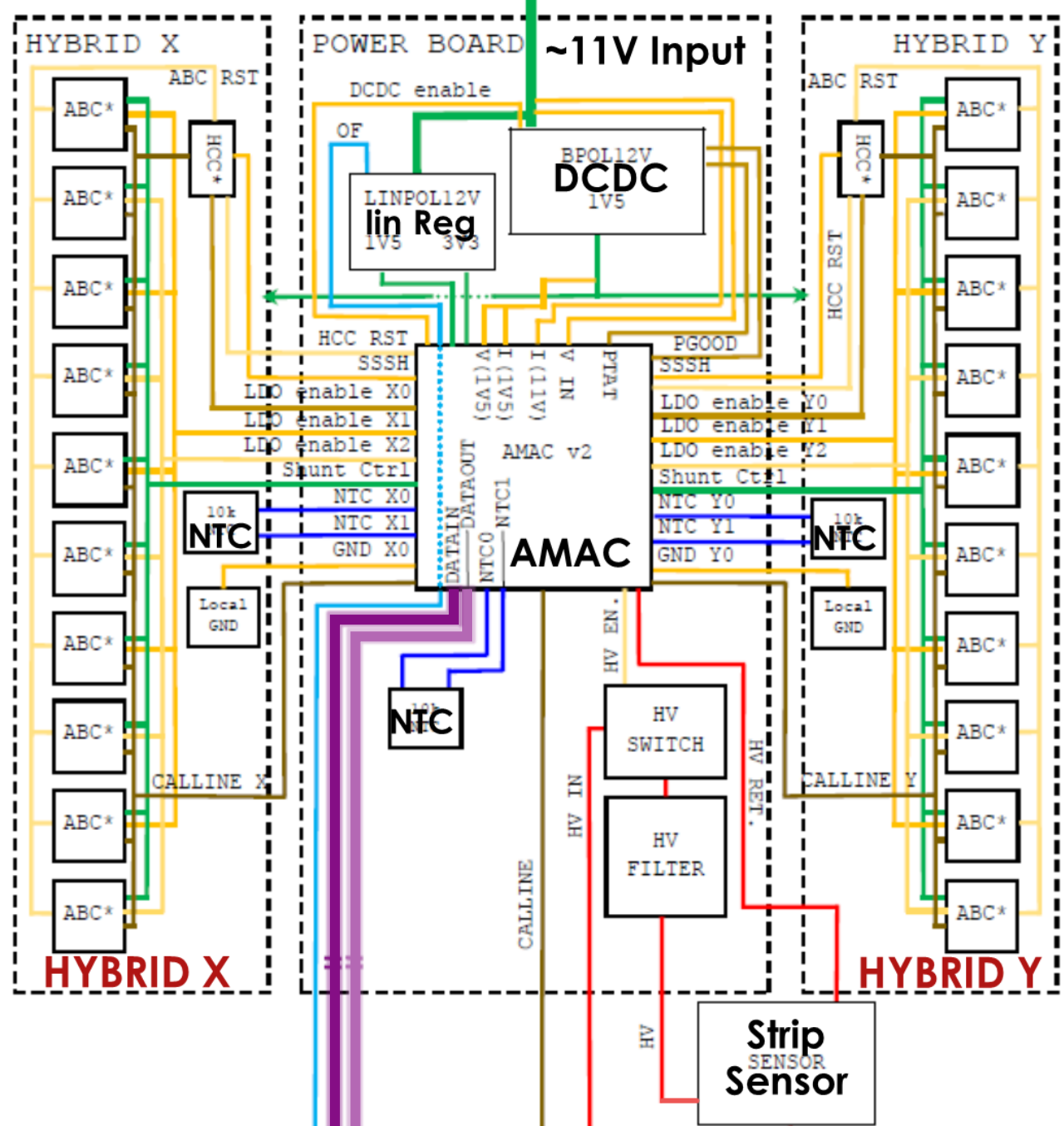
- Given the simple design, we can perform numerical fit for the individual resistance
- We could also use this to verify the how well is the manufacturer on producing resistors



NTCx_R_internal	171.65
NTCx_V_zero	243.85m
NTCx_Rdefault_Ohms	188.77k
NTCx_R0_Ohms	123.86k
NTCx_R1_Ohms	45.87k
NTCx_R2_Ohms	20.31k

(They agree with the designed value!)

Component Property	Value
NTCpb_sw_6_Ohms	14555.58796931094
NTCpb_sw_6_function	
Test Run Result	29.05.2020 try1 ✓



Reset in:

- SSSHx
- SSSH_y
- OFIn;

Resets Out

- 2 HCC Reset →
- OFOut →

Voltage DAC:

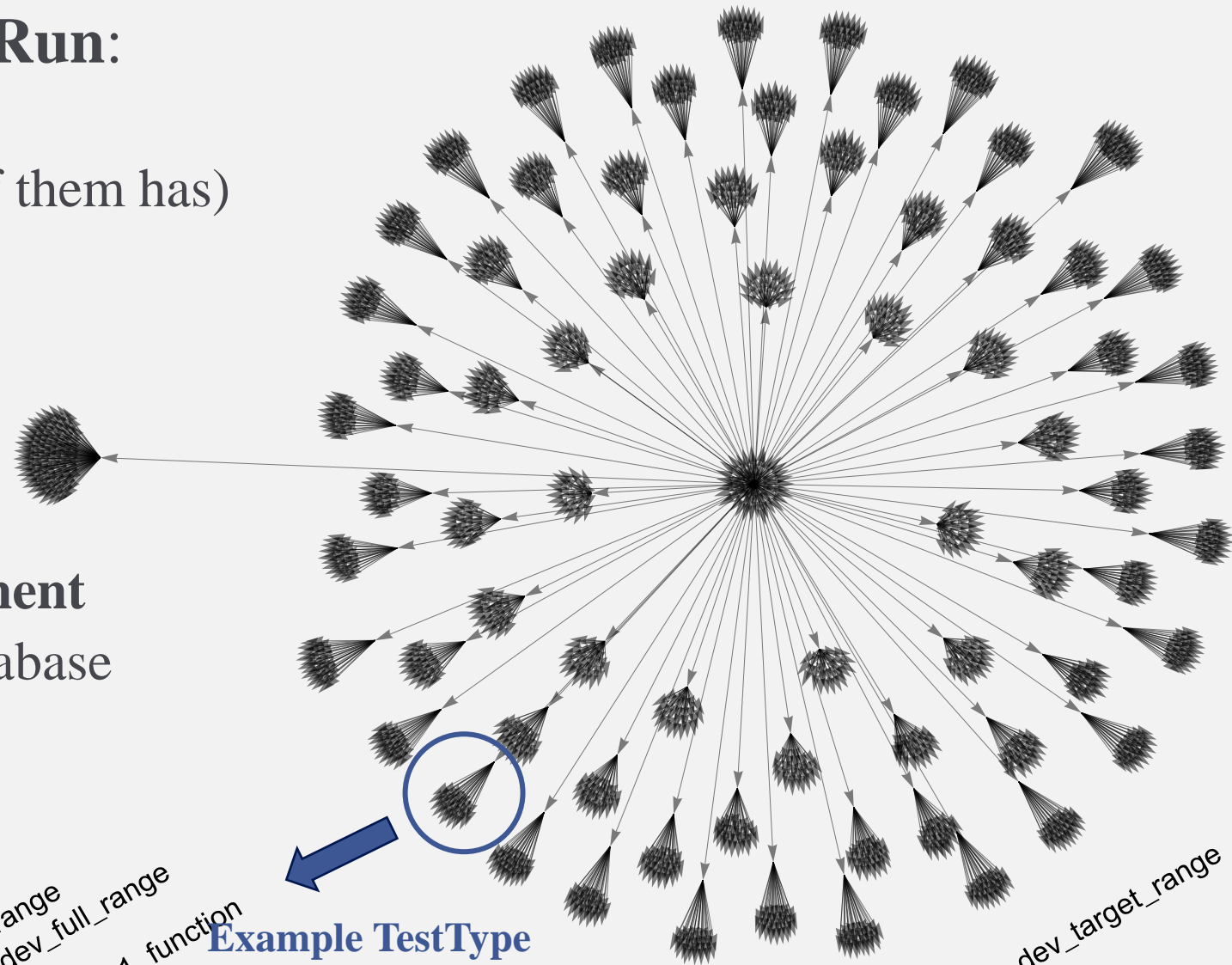
- Calx/y →;
- Shuntx/y →;

Communications lines:

- **Command Data In;**
- Command Data Response** →

- For each successful **AMAC - Test Run**:
 - 60 characterization **properties**
 - 72 **test** with fits and analysis (most of them has)
 - 8 **test parameters** per **test**
 - Each is an array of some type
 - 18 **test properties** per **test**
 - See next slides for example

- Database Structure Visualization ⇒
 - The center represent **AMAC Component**
 - Each arrow represent an object in database
 - Parameters, properties, tests, etc
 - Each cluster is a **TestType**



Vertex Style <| Test → ■ Test Parameter → ■ Test Property → ■ |>
 Vertex Shapes <| boolean → Circle, float → Triangle, integer → Square, string → Pentagon |>

Example TestType

